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*Electronics Market Research*

1462 East Grandview Street. • Mesa, AZ 85203 • U.S.A.

Tel: 480-968-3759 • Fax: 480-968-7145 • E-mail: [info@fwdconcepts.com](mailto:info@fwdconcepts.com)

[www.fwdconcepts.com](http://www.fwdconcepts.com)

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# **CELLPHONE CORE CHIP TRENDS**

Market Analysis of Baseband, Application Processor, RF & Power  
Management Chips

Author:

**Carter L. Horney**

Editor & Contributor:

**Will Strauss**

**Report No. 1111  
July, 2011**

## About the Author

**Carter L. Horney**, a recognized authority on microprocessor and DSP implementation in telecommunications, is the author of this report. Mr. Horney is an independent consultant and Forward Concepts Associate specializing in semiconductor product strategy and market planning. He was formerly Division Planner for Rockwell International's Digital Communications Division and earlier Strategic Marketing manager for Rockwell's Semiconductor Products Division. Mr. Horney was responsible for the product planning, which led Rockwell (now Conexant Systems) to dominate the worldwide FAX and high-speed modem chip market. He was appointed a Rockwell Engineering Fellow and received many commendations for outstanding achievement in Computer Architecture, Engineering, Technical Marketing, Product Planning and Customer Relations. Mr. Horney has a B.S. in Mathematics and Physics and an M.S. in Mathematics from Western Illinois University.

## About the Editor

**Will Strauss**, President of Forward Concepts, is the editor and significant contributor for this report. Mr. Strauss is internationally recognized as the leading authority on markets driven by digital signal processing (DSP), and wireless is the largest DSP market.

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